VAI has many years experience in semiconductor test applications. At VAI we offer test sockets and contactors, with unique solutions for various type of devices. We design and manufacture a broad product range - from sockets for RF micro lead frame packages and high power devices to high-speed ASICs with more than 2,000 pins. We are one of the few test socket design and manufacturers that also design probes pins / contactors.

VAI socket design process incorporates several rigorous phases. Our design team customizes test sockets using state-of-the-art computer-aided design (CAD) tools, including 3D mechanical modeling. We work closely with customer and involve them with all phases of project. After approval of designs, the product is sent to computer-aided manufacturing (CAM) for precision fabrication. We also provide load board footprint designing if the customer does not already have a load board design.

FEATURES
• Designed to fit Module.
• Allows for easy insertion and removal of module for upgrade, replacement and repair.
• Eliminates damage to valuable PCB.
• Perfect for high volume production applications and prototypes.
• Good compliance between the device & contacts
• Uses a special surface mounting to your printed circuit board.
• Special prototyping adapters designed on request allowing socket to be plugged onto standard prototyping boards.
• The Socket material allows for device alignment with high wear resistance & low thermal coefficient of thermal expansion.
• The socket body utilize coarse & fine alignment with tapered guides to ensure ease of entry.

APPLICATIONS
• Hand-Test
• Prototyping
• Qualification
• Development
• Device Stability
• Mass Production
• Future Upgrades
• Allocation Issues

LEAD PITCH
• Smaller pitch 0.4mm

MATERIALS
• Torlon 4203
• Torlon 5530
• Ceramic Peek
• Vespel
• Semitron
• Krefine
• Ultem 2300

COMPLIANCE
• RoH Compliance

Socket Device Type:
- BGA, uBGA, VFGAB, FCTEBGA, WLCPS, LFBGAQFP, QFN, VFQFN, VFQFPN, LGA, TQFP, VQFN, VQFPN, FPBGA, MLP, WPLGA, LGA, CSP
- SOT package, TO Package, (TO package with Kelvin contact) SOIC package (SOIC with Kelvin contact) TSOP package, SOP, MSOP
- Edge card, Strip test socket
VAI Test Socket

- Dual Site Test Socket
- Quad Site Test Socket
- SOIC1 – 2 in 1 test socket (for manual and auto test)
- Quad Site Test Socket
- Package: BGA
- Package: TSSOP
- Manual Lid for BGA package
- Manual Lid - Latch
- Manual Lid - Rotary
- QFN – top metal plate
- Manual Test
- Auto Test with manual lid removed
- Test socket for RX-LG package
- TSSOP test contactor
- Kelvin contact
- TSSOP & SOIC test contactor
- Kelvin / Non Kelvin contact
- TO-258
- High power with heat sink
- Strip contactor
- SOIC – manual test
- Test contactor
- For MSOP 8 lead
- QPF48
- Test contactor
- Package: VFQFN
- Package: FCBGA
- Package: QFP with lid
- VA Innovation Pte Ltd
  Blk 5004 Ang Mo Kio Ave 5 #04-10 TECHplace II Singapore 569872